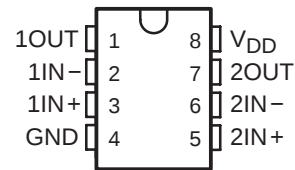


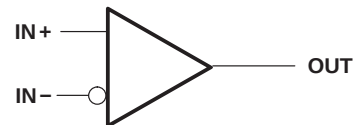
- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree†**
- **Push-Pull CMOS Output Drives Capacitive Loads Without Pullup Resistor, $I_O = \pm 8$ mA**
- **Very Low Power . . . 100 μ W Typ at 5 V**
- **Fast Response Time . . . $t_{PLH} = 2.7$ μ s Typ With 5-mV Overdrive**
- **Single-Supply Operation . . . 4 V to 16 V**
- **On-Chip ESD Protection**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

**D PACKAGE
(TOP VIEW)**



symbol (each comparator)



description

The TLC3702 consists of two independent micropower voltage comparators designed to operate from a single supply and be compatible with modern HCMOS logic systems. They are functionally similar to the LM339 but use one-twentieth of the power for similar response times. The push-pull CMOS output stage drives capacitive loads directly without a power-consuming pullup resistor to achieve the stated response time. Eliminating the pullup resistor not only reduces power dissipation, but also saves board space and component cost. The output stage is also fully compatible with TTL requirements.

Texas Instruments LinCMOS™ process offers superior analog performance to standard CMOS processes. Along with the standard CMOS advantages of low power without sacrificing speed, high input impedance, and low bias currents, the LinCMOS™ process offers extremely stable input offset voltages with large differential input voltages. This characteristic makes it possible to build reliable CMOS comparators.

ORDERING INFORMATION

T _A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOP – D	Tape and reel	TLC3702MDREP	3702ME

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinCMOS is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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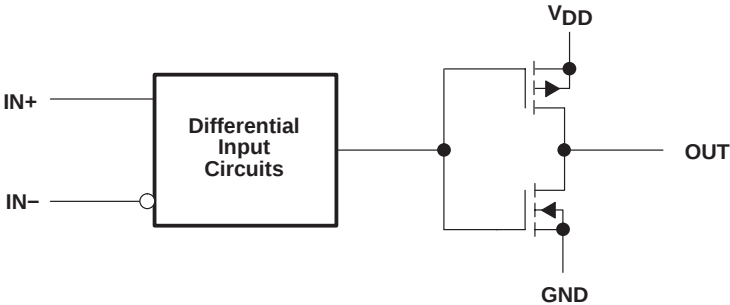
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functional block diagram (each comparator)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD} (see Note 1)	–0.3 V to 18 V
Differential input voltage, V_{ID} (see Note 2)	±18 V
Input voltage range, V_I	–0.3 V to V_{DD}
Output voltage range, V_O	– 0.3 V to V_{DD}
Input current, I_I	±5 mA
Output current, I_O (each output)	±20 mA
Total supply current into V_{DD}	40 mA
Total current out of GND	40 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	–55°C to 125°C
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential voltages, are with respect to network ground.
 2. Differential voltages are at IN+ with respect to IN–.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^{\circ}\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^{\circ}\text{C}$	$T_A = 70^{\circ}\text{C}$ POWER RATING	$T_A = 85^{\circ}\text{C}$ POWER RATING	$T_A = 125^{\circ}\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	4	5	16	V
Common-mode input voltage, V_{IC}	0		$V_{DD} - 1.5$	V
High-level output current, I_{OH}			–20	mA
Low-level output current, I_{OL}			20	mA
Operating free-air temperature, T_A	–55		125	°C

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electrical characteristics at specified operating free-air temperature, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	T_A	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	$V_{DD} = 5\text{ V to }10\text{ V}$, $V_{IC} = V_{ICRmin}$, See Note 3	25°C		1.2	5	mV
			–55°C to 125°C			10	
I_{IO}	Input offset current	$V_{IC} = 2.5\text{ V}$	25°C		1		pA
			125°C			15	nA
I_{IB}	Input bias current	$V_{IC} = 2.5\text{ V}$	25°C		5		pA
			125°C			30	nA
V_{ICR}	Common-mode input voltage range		25°C	0 to $V_{DD} - 1$			V
			–55°C to 125°C	0 to $V_{DD} - 1.5$			
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$	25°C		84		dB
			125°C		83		
			–55°C		82		
k_{SVR}	Supply-voltage rejection ratio	$V_{DD} = 5\text{ V to }10\text{ V}$	25°C		85		dB
			125°C		85		
			– 55°C		82		
V_{OH}	High-level output voltage	$V_{ID} = 1\text{ V}$, $I_{OH} = -4\text{ mA}$	25°C	4.5	4.7		V
			125°C	4.2			
V_{OL}	Low-level output voltage	$V_{ID} = -1\text{ V}$, $I_{OH} = -4\text{ mA}$	25°C		210	300	mV
			125°C			500	
I_{DD}	Supply current (both comparators)	Outputs low, No load	25°C		18	40	μA
			–55°C to 125°C			90	

† All characteristics are measured with zero common-mode voltage unless otherwise noted.

NOTE 3. The offset voltage limits given are the maximum values required to drive the output up to 4.5 V or down to 0.3 V.



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switching characteristics, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low-to-high-level output [†]	f = 10 kHz, C _L = 50 pF	Overdrive = 2 mV	4.5		μs	
			Overdrive = 5 mV	2.7			
			Overdrive = 10 mV	1.9			
			Overdrive = 20 mV	1.4			
			Overdrive = 40 mV	1.1			
t _{PHL}	Propagation delay time, high-to-low-level output [†]	V _I = 1.4 V step at IN+		1.1		μs	
		f = 10 kHz, C _L = 50 pF	Overdrive = 2 mV	4			
			Overdrive = 5 mV	2.3			
			Overdrive = 10 mV	1.5			
			Overdrive = 20 mV	0.95			
			Overdrive = 40 mV	0.65			
		V _I = 1.4 V step at IN+		0.15			
t _f	Fall time	f = 10 kHz, C _L = 50 pF	Overdrive = 50 mV	50		ns	
t _r	Rise time	f = 10 kHz, C _L = 50 pF	Overdrive = 50 mV	125		ns	

† Simultaneous switching of inputs causes degradation in output response.

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PRINCIPLES OF OPERATION

input protection circuit operation

Texas Instruments patented protection circuitry allows for both positive- and negative-going ESD transients. These transients are characterized by extremely fast rise times and usually low energies, and can occur both when the device has all pins open and when it is installed in a circuit.

positive ESD transients

Initial positive charged energy is shunted through Q1 to V_{SS} . Q1 turns on when the voltage at the input rises above the voltage on the V_{DD} pin by a value equal to the V_{BE} of Q1. The base current increases through R2 with input current as Q1 saturates. The base current through R2 forces the voltage at the drain and gate of Q2 to exceed its threshold level ($V_T \sim 22$ to 26 V) and turn Q2 on. The shunted input current through Q1 to V_{SS} is now shunted through the n-channel enhancement-type MOSFET Q2 to V_{SS} . If the voltage on the input pin continues to rise, the breakdown voltage of the zener diode D3 is exceeded and all remaining energy is dissipated in R1 and D3. The breakdown voltage of D3 is designed to be 24 V to 27 V, which is well below the gate-oxide voltage of the circuit to be protected.

negative ESD transients

The negative charged ESD transients are shunted directly through D1. Additional energy is dissipated in R1 and D2 as D2 becomes forward biased. The voltage seen by the protected circuit is -0.3 V to -1 V (the forward voltage of D1 and D2).

circuit-design considerations

LinCMOS™ products are being used in actual circuit environments that have input voltages that exceed the recommended common-mode input voltage range and activate the input protection circuit. Even under normal operation, these conditions occur during circuit power up or power down, and in many cases, when the device is being used for a signal conditioning function. The input voltages can exceed V_{ICR} and not damage the device only if the inputs are current limited. The recommended current limit shown on most product data sheets is ± 5 mA. Figure 2 and Figure 3 show typical characteristics for input voltage versus input current.

Normal operation and correct output state can be expected even when the input voltage exceeds the positive supply voltage. Again, the input current should be externally limited even though internal positive current limiting is achieved in the input protection circuit by the action of Q1. When Q1 is on, it saturates and limits the current to approximately 5-mA collector current by design. When saturated, Q1 base current increases with input current. This base current is forced into the V_{DD} pin and into the device I_{DD} or the V_{DD} supply through R2 producing the current limiting effects shown in Figure 2. This internal limiting lasts only as long as the input voltage is below the V_T of Q2.

When the input voltage exceeds the negative supply voltage, normal operation is affected and output voltage states may not be correct. Also, the isolation between channels of multiple devices (duals and quads) can be severely affected. External current limiting must be used since this current is directly shunted by D1 and D2 and no internal limiting is achieved. If normal output voltage states are required, an external input voltage clamp is required (see Figure 4).



PRINCIPLES OF OPERATION

circuit-design considerations (continued)

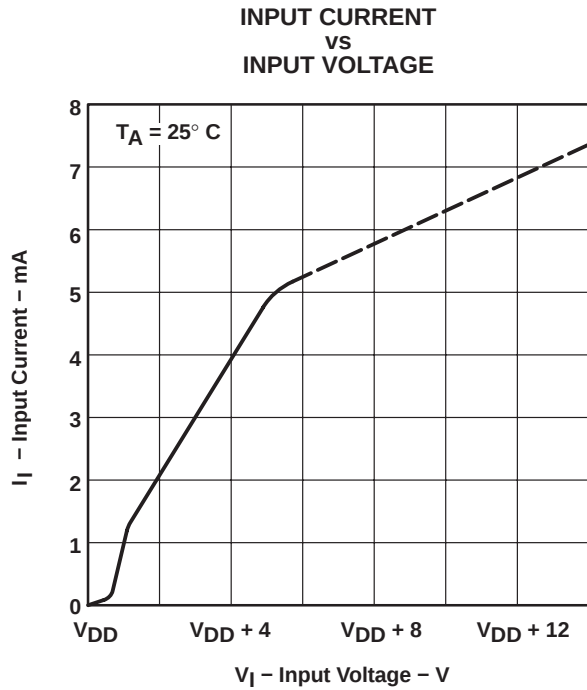


Figure 2

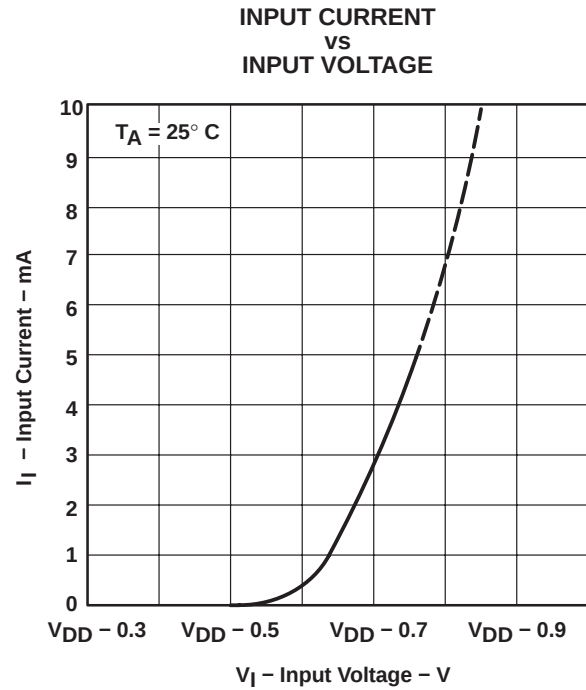
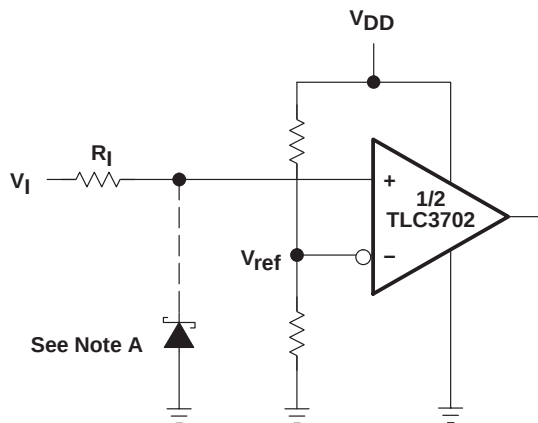


Figure 3



Positive Voltage Input Current Limit :

$$R_I = \frac{V_I - V_{DD} - 0.3 \text{ V}}{5 \text{ mA}}$$

Negative Voltage Input Current Limit :

$$R_I = \frac{-V_I - V_{DD} - (-0.3 \text{ V})}{5 \text{ mA}}$$

NOTE A: If the correct input state is required when the negative input exceeds GND, a Schottky clamp is required.

Figure 4. Typical Input Current-Limiting Configuration for a LinCMOS™ Comparator

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PARAMETER MEASUREMENT INFORMATION

The TLC3702 contains a digital output stage which, if held in the linear region of the transfer curve, can cause damage to the device. Conventional operational amplifier/comparator testing incorporates the use of a servo loop which is designed to force the device output to a level within this linear region. Since the servo-loop method of testing cannot be used, we offer the following alternatives for measuring parameters such as input offset voltage, common-mode rejection, etc.

To verify that the input offset voltage falls within the limits specified, the limit value is applied to the input as shown in Figure 5(a). With the noninverting input positive with respect to the inverting input, the output should be high. With the input polarity reversed, the output should be low.

A similar test can be made to verify the input offset voltage at the common-mode extremes. The supply voltages can be slewed to provide greater accuracy, as shown in Figure 5(b) for the V_{ICR} test. This slewing is done instead of changing the input voltages.

A close approximation of the input offset voltage can be obtained by using a binary search method to vary the differential input voltage while monitoring the output state. When the applied input voltage differential is equal, but opposite in polarity, to the input offset voltage, the output changes states.

Figure 6 illustrates a practical circuit for direct dc measurement of input offset voltage that does not bias the comparator in the linear region. The circuit consists of a switching mode servo loop in which IC1a generates a triangular waveform of approximately 20-mV amplitude. IC1b acts as a buffer, with C2 and R4 removing any residual dc offset. The signal is then applied to the inverting input of the comparator under test, while the noninverting input is driven by the output of the integrator formed by IC1c through the voltage divider formed by R8 and R9. The loop reaches a stable operating point when the output of the comparator under test has a duty cycle of exactly 50%, which can only occur when the incoming triangle wave is sliced symmetrically or when the voltage at the noninverting input exactly equals the input offset voltage.

Voltage dividers R8 and R9 provide an increase in input offset voltage by a factor of 100 to make measurement easier. The values of R5, R7, R8, and R9 can significantly influence the accuracy of the reading; therefore, it is suggested that their tolerance level be one percent or lower.

Measuring the extremely low values of input current requires isolation from all other sources of leakage current and compensation for the leakage of the test socket and board. With a good picoammeter, the socket and board leakage can be measured with no device in the socket. Subsequently, this open socket leakage value can be subtracted from the measurement obtained with a device in the socket to obtain the actual input current of the device.

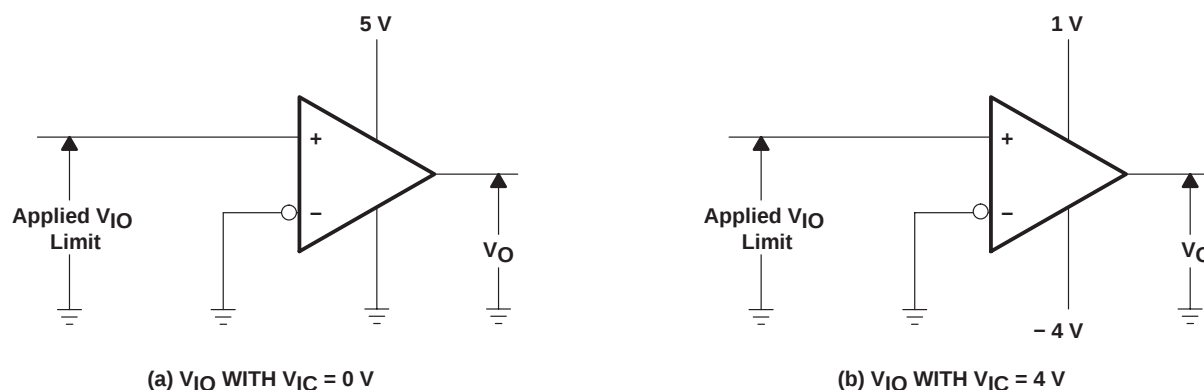


Figure 5. Method for Verifying That Input Offset Voltage Is Within Specified Limits

PARAMETER MEASUREMENT INFORMATION

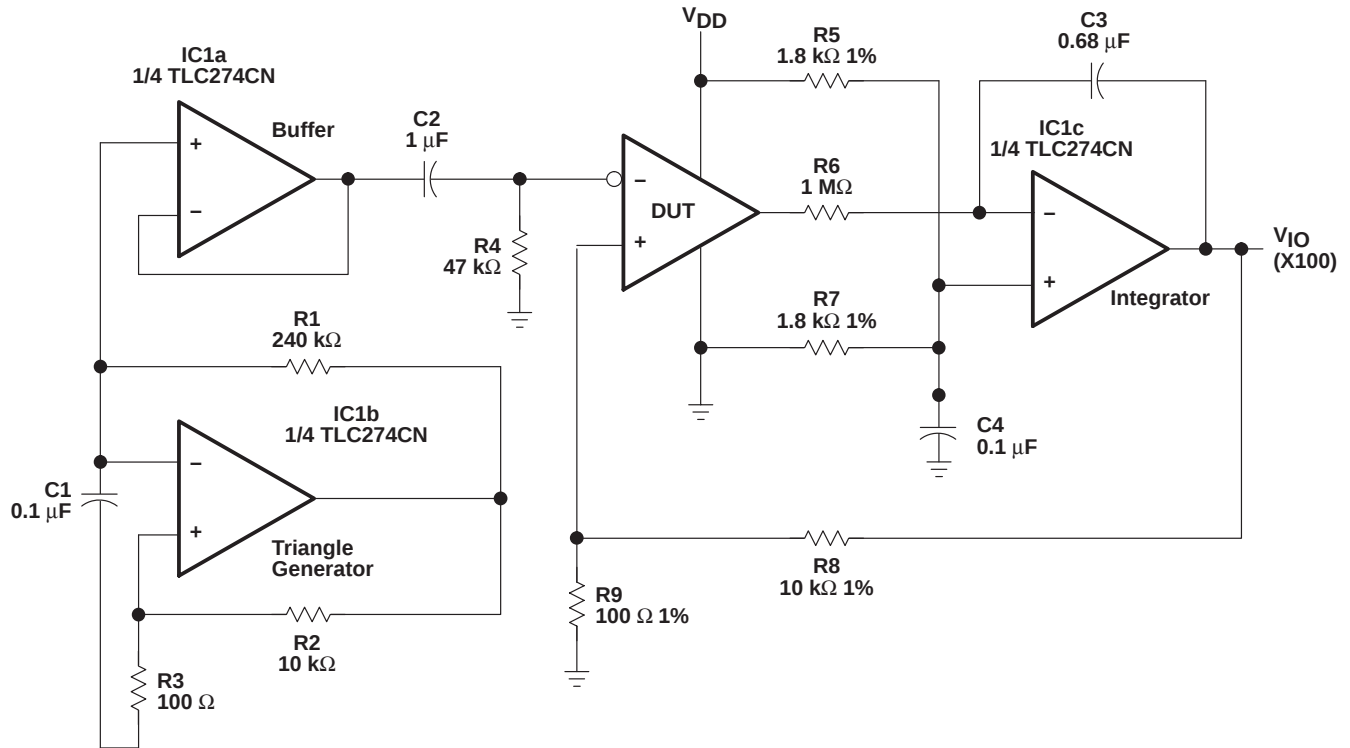


Figure 6. Circuit for Input Offset Voltage Measurement

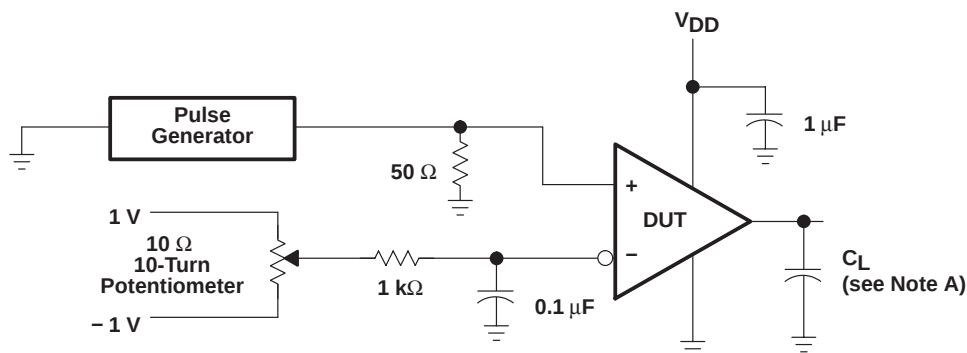
Response time is defined as the interval between the application of an input step function and the instant when the output reaches 50% of its maximum value. Response time for the low-to-high-level output is measured from the leading edge of the input pulse, while response time for the high-to-low-level output is measured from the trailing edge of the input pulse. Response time measurement at low input signal levels can be greatly affected by the input offset voltage. The offset voltage should be balanced by the adjustment at the inverting input as shown in Figure 7, so that the circuit is just at the transition point. A low signal, for example 105-mV or 5-mV overdrive, causes the output to change state.

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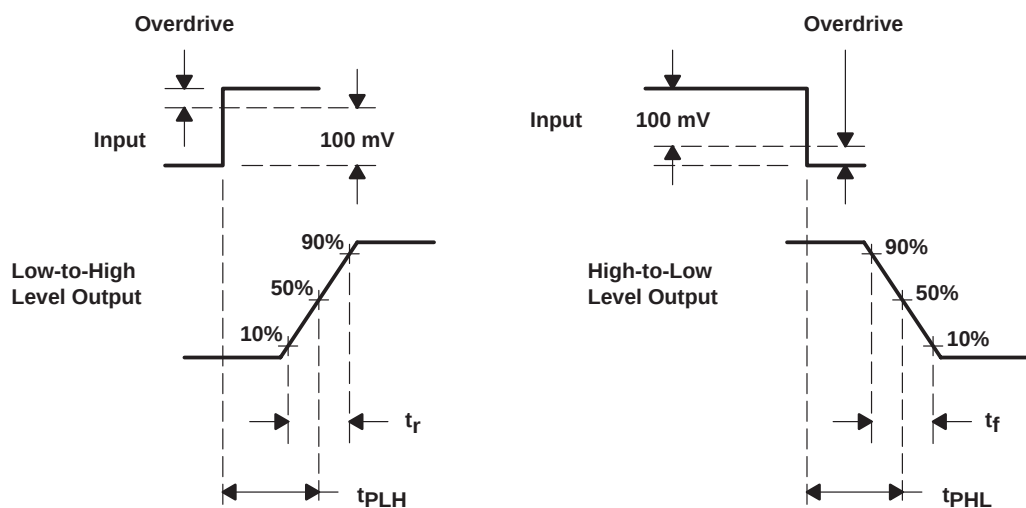
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PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTE A: C_L includes probe and jig capacitance.

Figure 7. Response, Rise, and Fall Times Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS†

Table of Graphs

			FIGURE
V_{IO}	Input offset voltage	Distribution	8
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V_{OH}	High-level output current	vs Free-air temperature	12
		vs High-level output current	13
V_{OL}	Low-level output voltage	vs Low-level output current	14
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t_t	Transition time	vs Load capacitance	16
	Supply current response	vs Time	17
	Low-to-high-level output response	Low-to-high level output propagation delay time	18
	High-to-low level output response	High-to-low level output propagation delay time	19
t_{PLH}	Low-to-high level output propagation delay time	vs Supply voltage	20
t_{PHL}	High-to-low level output propagation delay time	vs Supply voltage	21
I_{DD}	Supply current	vs Frequency	22
		vs Supply voltage	23
		vs Free-air temperature	24

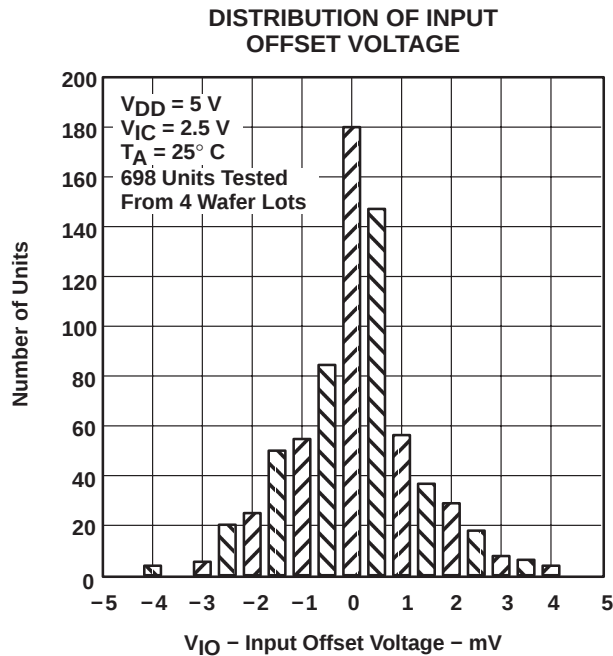


Figure 8

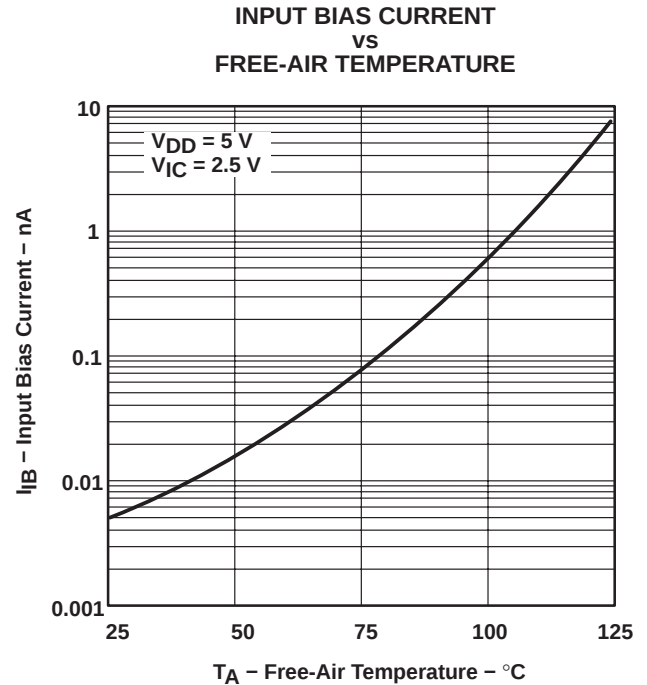


Figure 9

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

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TYPICAL CHARACTERISTICS†

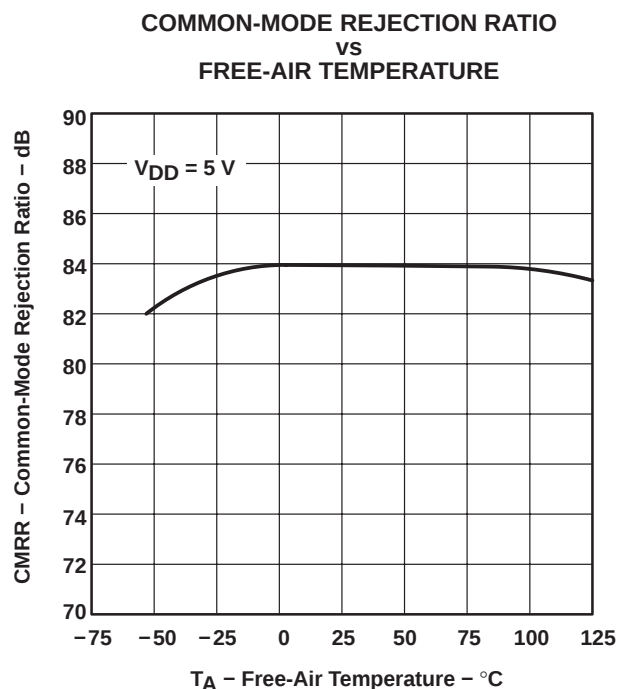


Figure 10

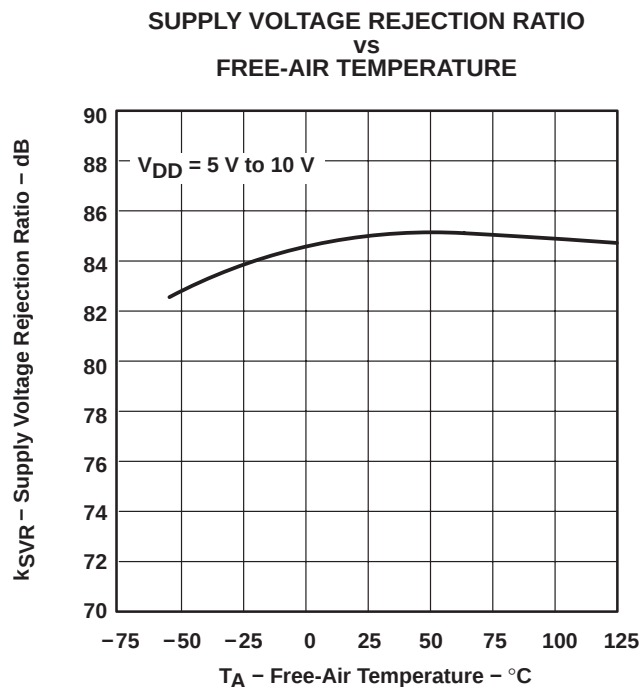


Figure 11

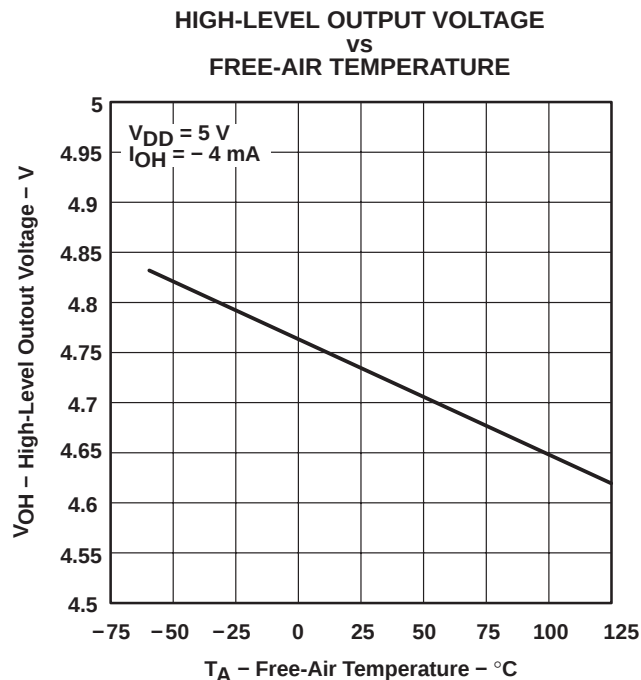


Figure 12

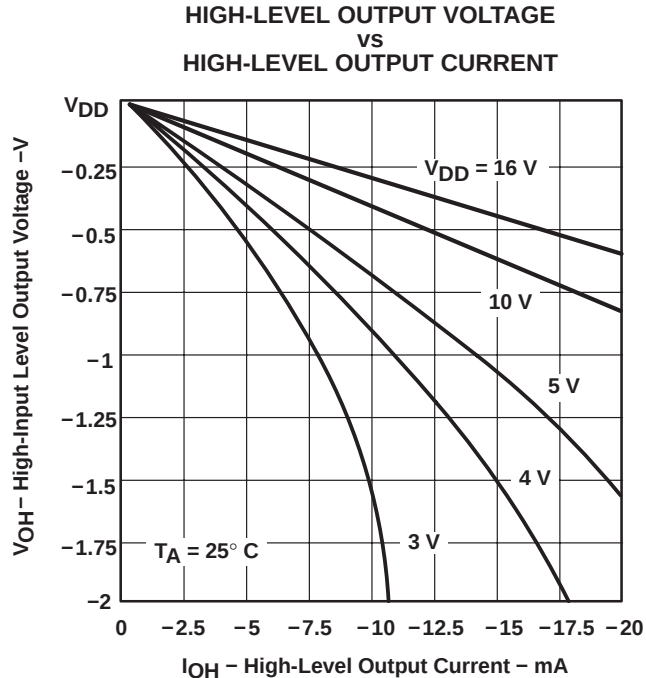
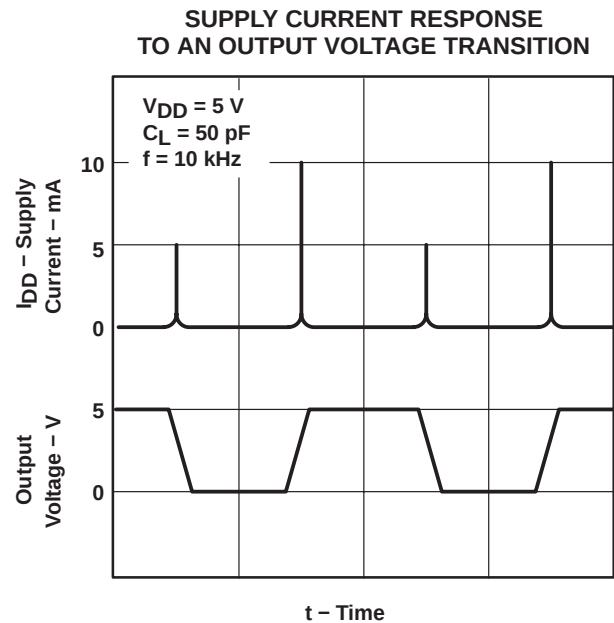
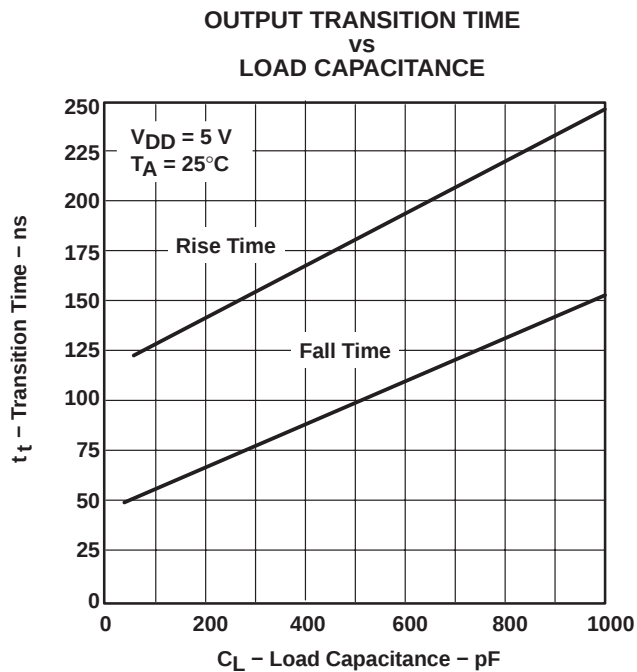
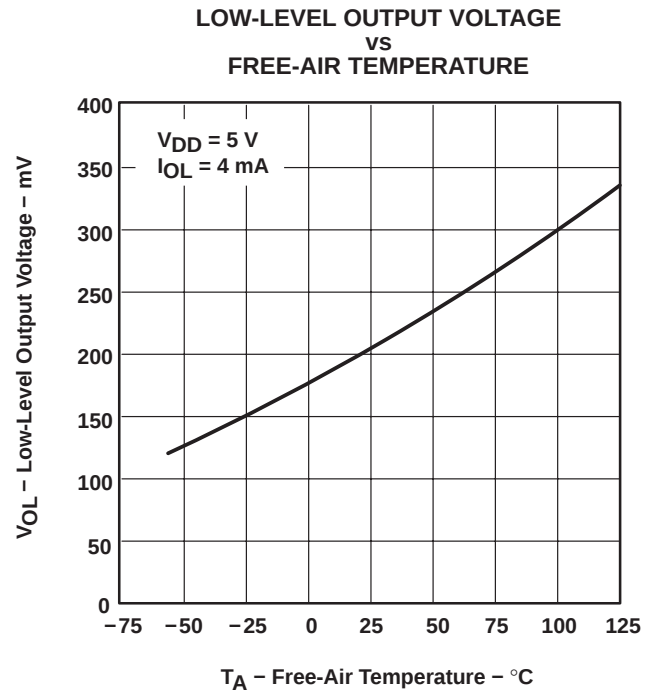
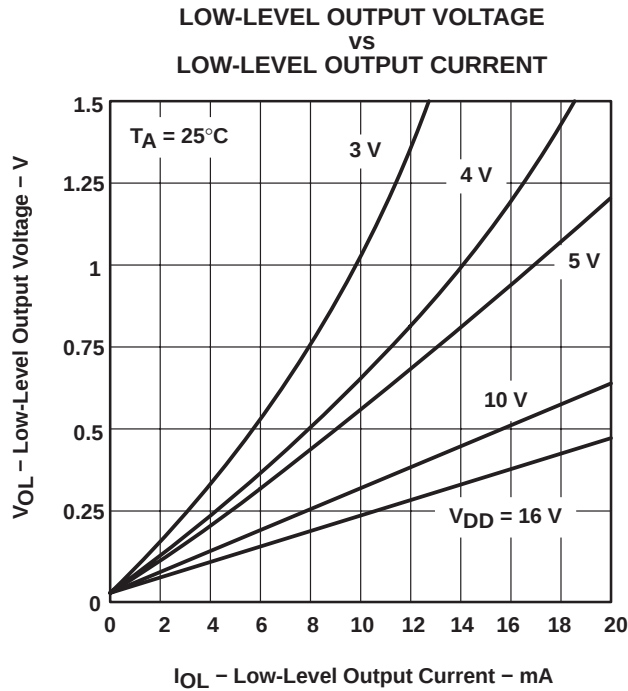


Figure 13

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†



† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

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TYPICAL CHARACTERISTICS

LOW-TO-HIGH-LEVEL OUTPUT RESPONSE
FOR VARIOUS INPUT OVERDRIVES

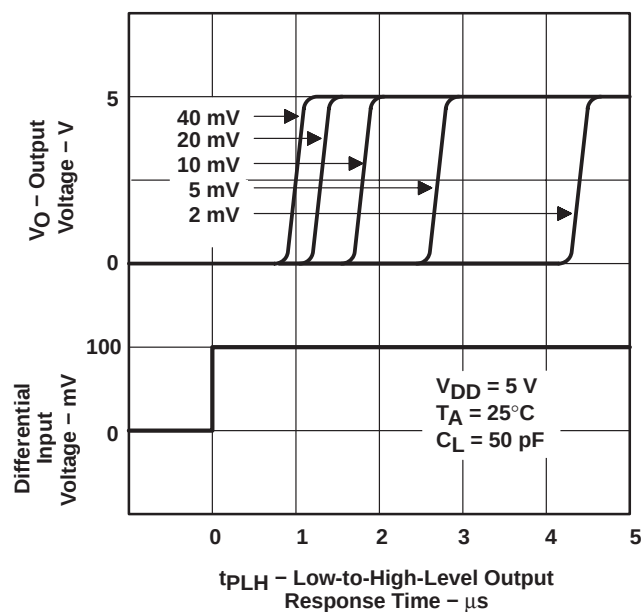


Figure 18

HIGH-TO-LOW-LEVEL OUTPUT RESPONSE
FOR VARIOUS INPUT OVERDRIVES

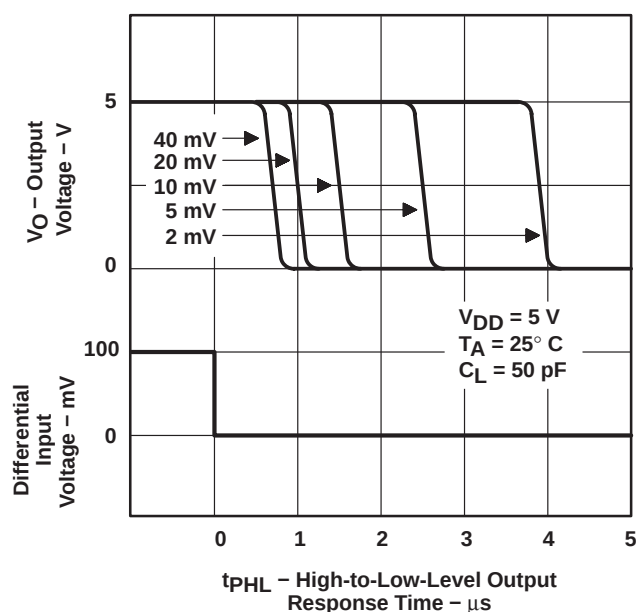


Figure 19

LOW-TO-HIGH-LEVEL
OUTPUT RESPONSE TIME
vs
SUPPLY VOLTAGE

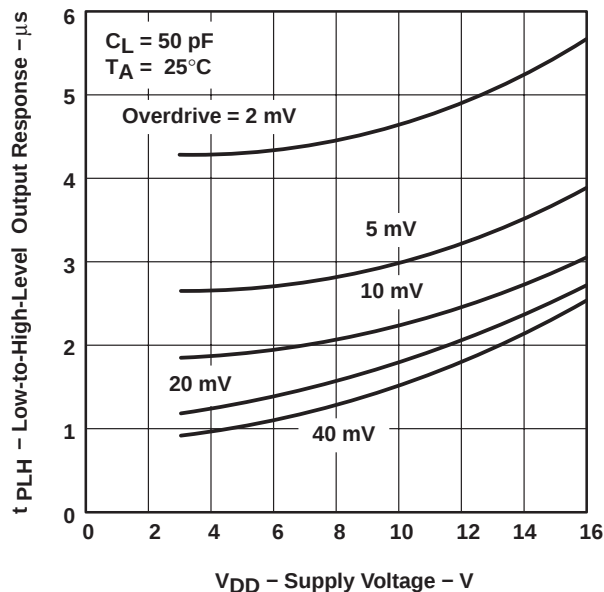


Figure 20

HIGH-TO-LOW-LEVEL
OUTPUT RESPONSE TIME
vs
SUPPLY VOLTAGE

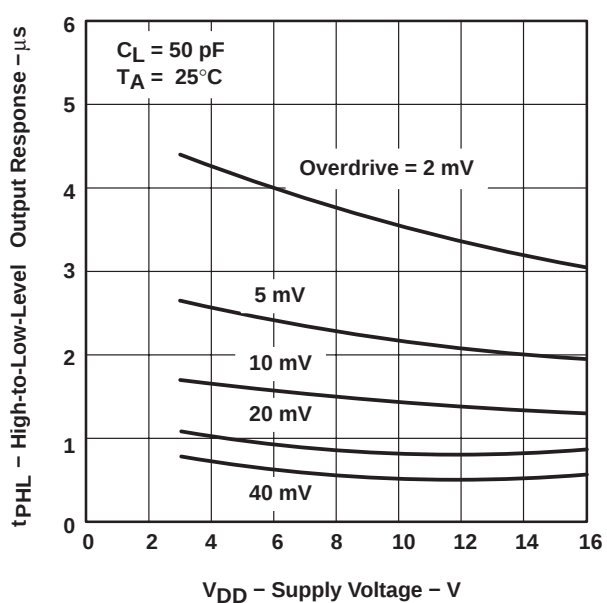
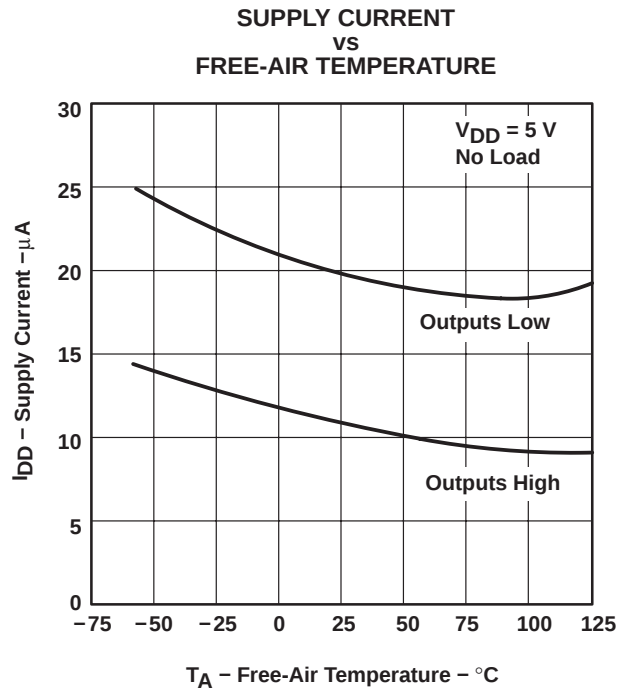
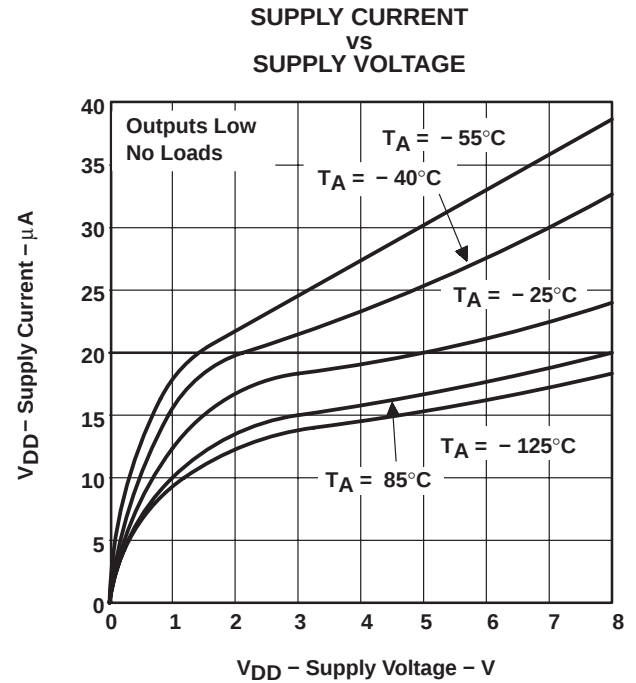
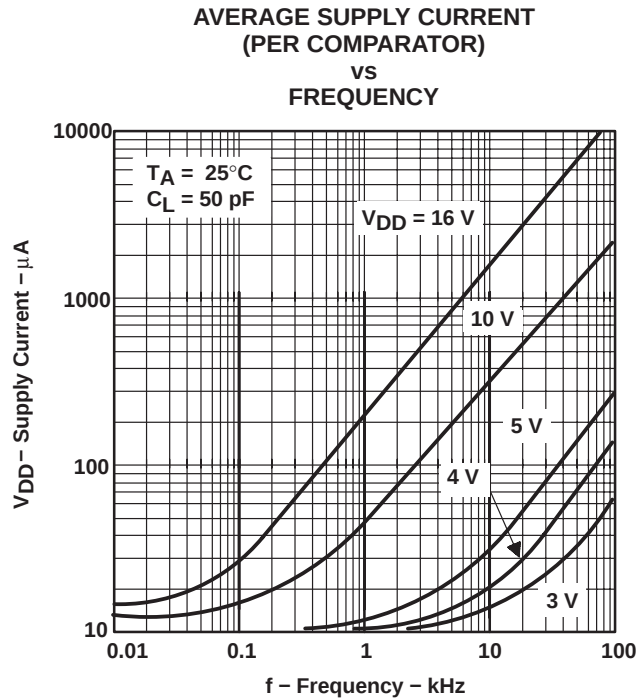


Figure 21

TYPICAL CHARACTERISTICS†



† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

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APPLICATION INFORMATION

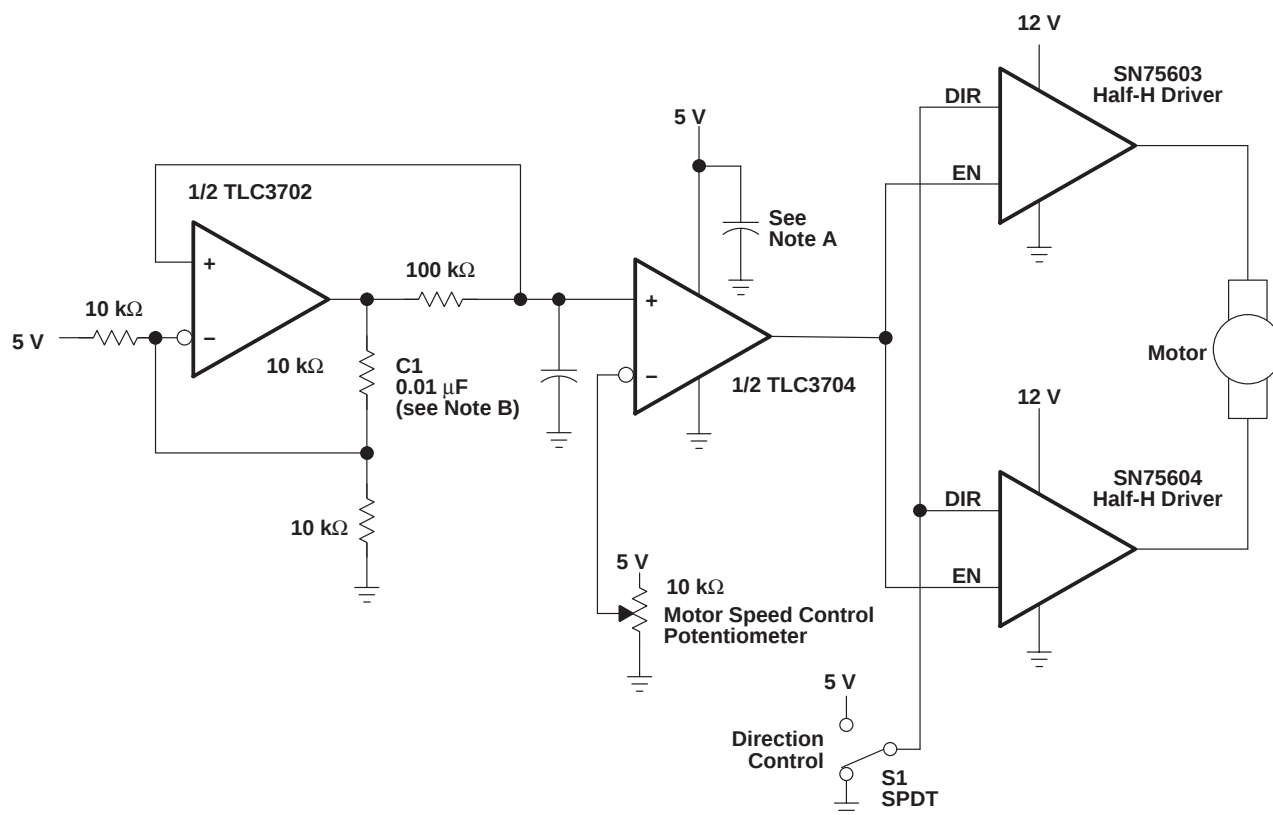
The inputs should always remain within the supply rails in order to avoid forward biasing the diodes in the electrostatic discharge (ESD) protection structure. If either input exceeds this range, the device is not damaged as long as the input is limited to less than 5 mA. To maintain the expected output state, the inputs must remain within the common-mode range. For example, at 25°C with $V_{DD} = 5\text{ V}$, both inputs must remain between -0.2 V and 4 V to ensure proper device operation.

To ensure reliable operation, the supply should be decoupled with a capacitor ($0.1\text{ }\mu\text{F}$) that is positioned as close to the device as possible.

The TLC3702 has internal ESD-protection circuits that prevent functional failures at voltages up to 2000 V as tested under MIL-STD-883C, Method 3015.2; however, care should be exercised in handling these devices as exposure to ESD may result in the degradation of the device parametric performance.

Table of Applications

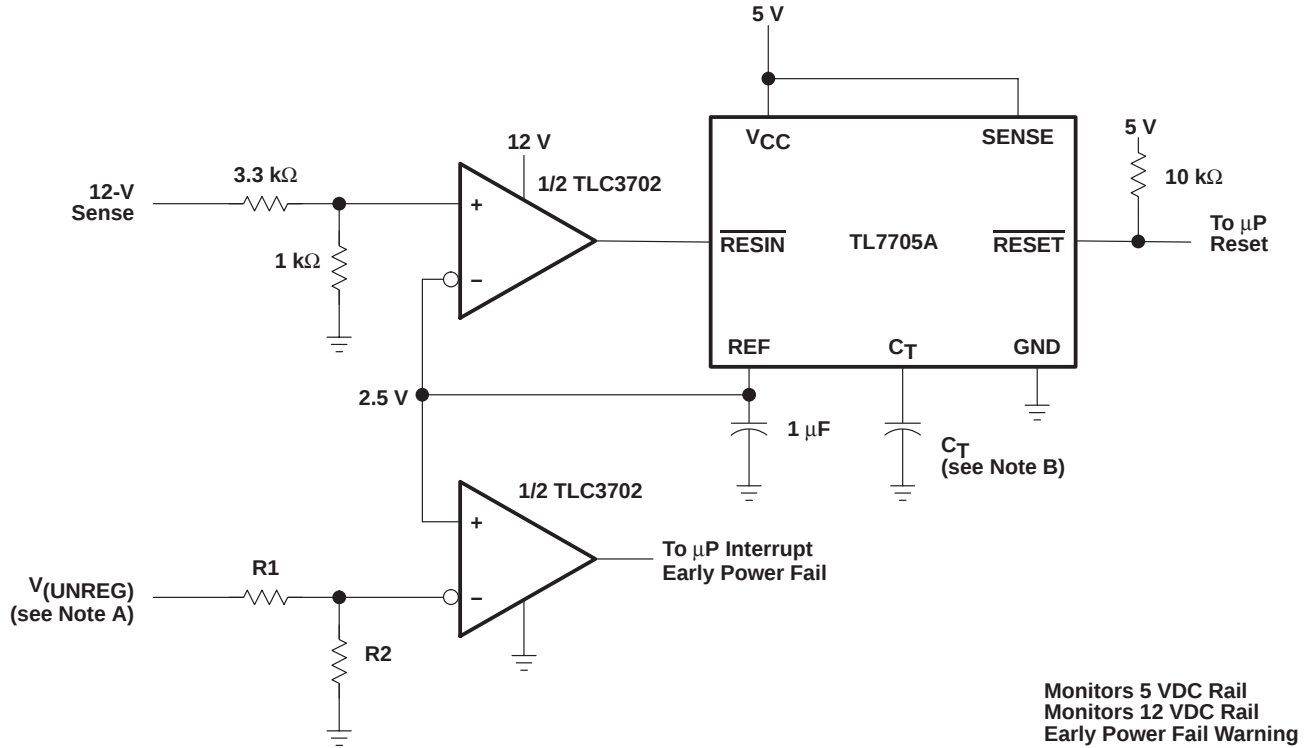
	FIGURE
Pulse-width-modulated motor speed controller	25
Enhanced supply supervisor	26
Two-phase nonoverlapping clock generator	27
Micropower switching regulator	28



NOTES: A. The recommended minimum capacitance is $10\text{ }\mu\text{F}$ to eliminate common ground switching noise.
B. Adjust C1 for change in oscillator frequency.

Figure 25. Pulse-Width-Modulated Motor Speed Controller

APPLICATION INFORMATION



NOTES: A. $V_{(UNREG)} = 2.5 \frac{(R1 + R2)}{R2}$

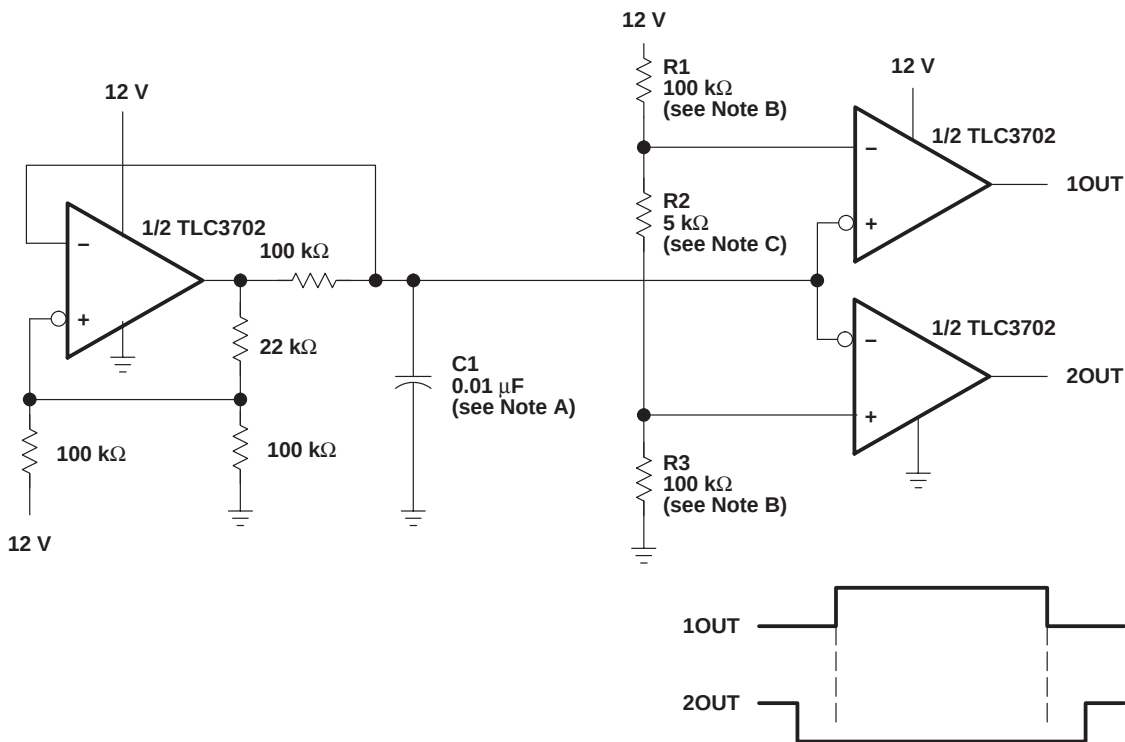
B. The value of C_T determines the time delay of reset.

Figure 26. Enhanced Supply Supervisor

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APPLICATION INFORMATION



NOTES: A. Adjust C1 for a change in oscillator frequency where:

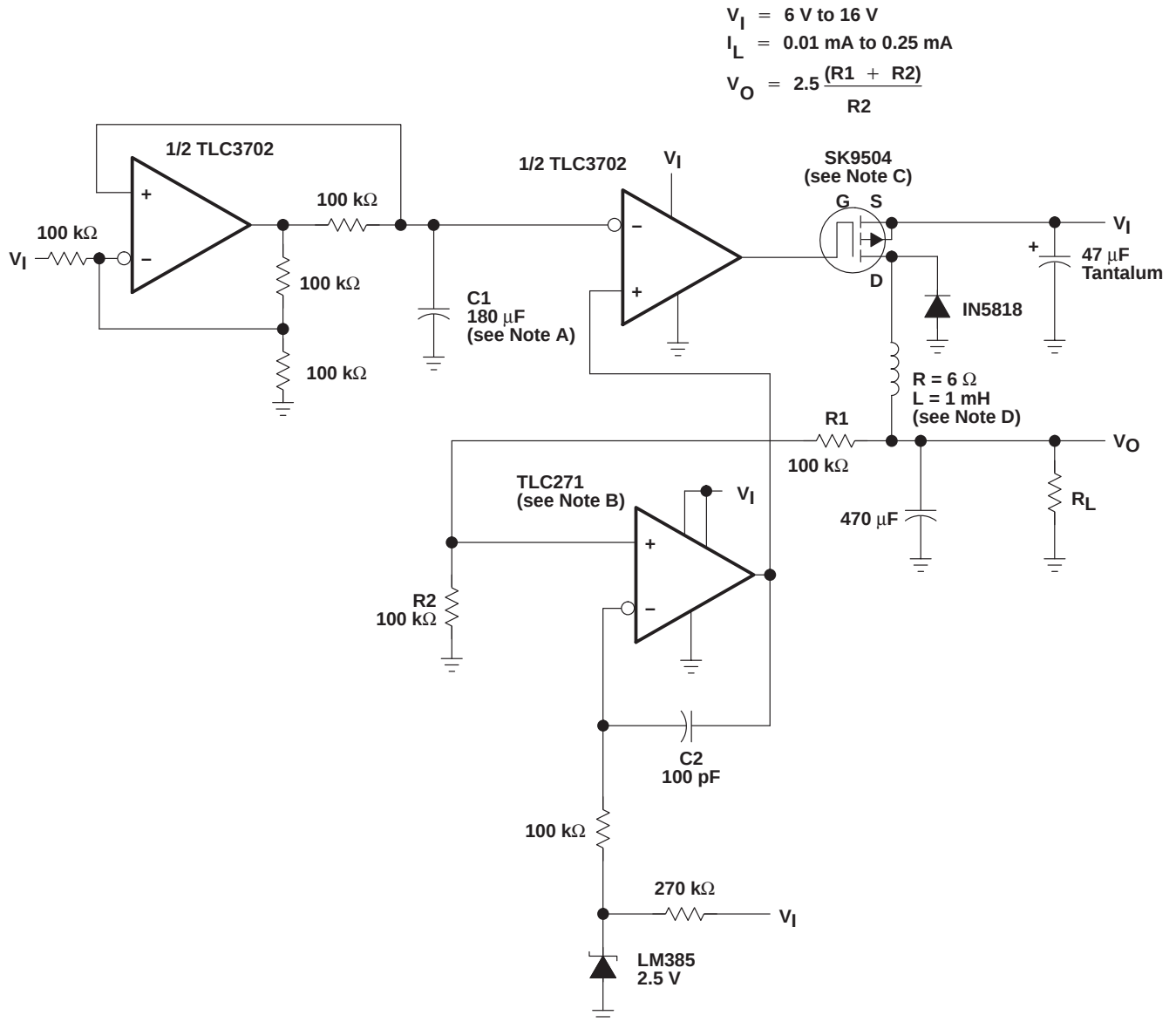
$$1/f = 1.85(100 \text{ k}\Omega)C_1$$

B. Adjust R1 and R3 to change duty cycle

C. Adjust R2 to change deadtime

Figure 27. Two-Phase Nonoverlapping Clock Generator

APPLICATION INFORMATION



- NOTES: A. Adjust C1 for a change in oscillator frequency
 B. TLC271 – Tie pin 8 to pin 7 for low bias operation
 C. SK9504 – $V_{DS} = 40\text{ V}$
 $I_{DS} = 1\text{ A}$
 D. To achieve microampere current drive, the inductance of the circuit must be increased.

Figure 28. Micropower Switching Regulator

TLC3702-EP

DUAL MICROPOWER LinCMOS™ VOLTAGE COMPARATOR

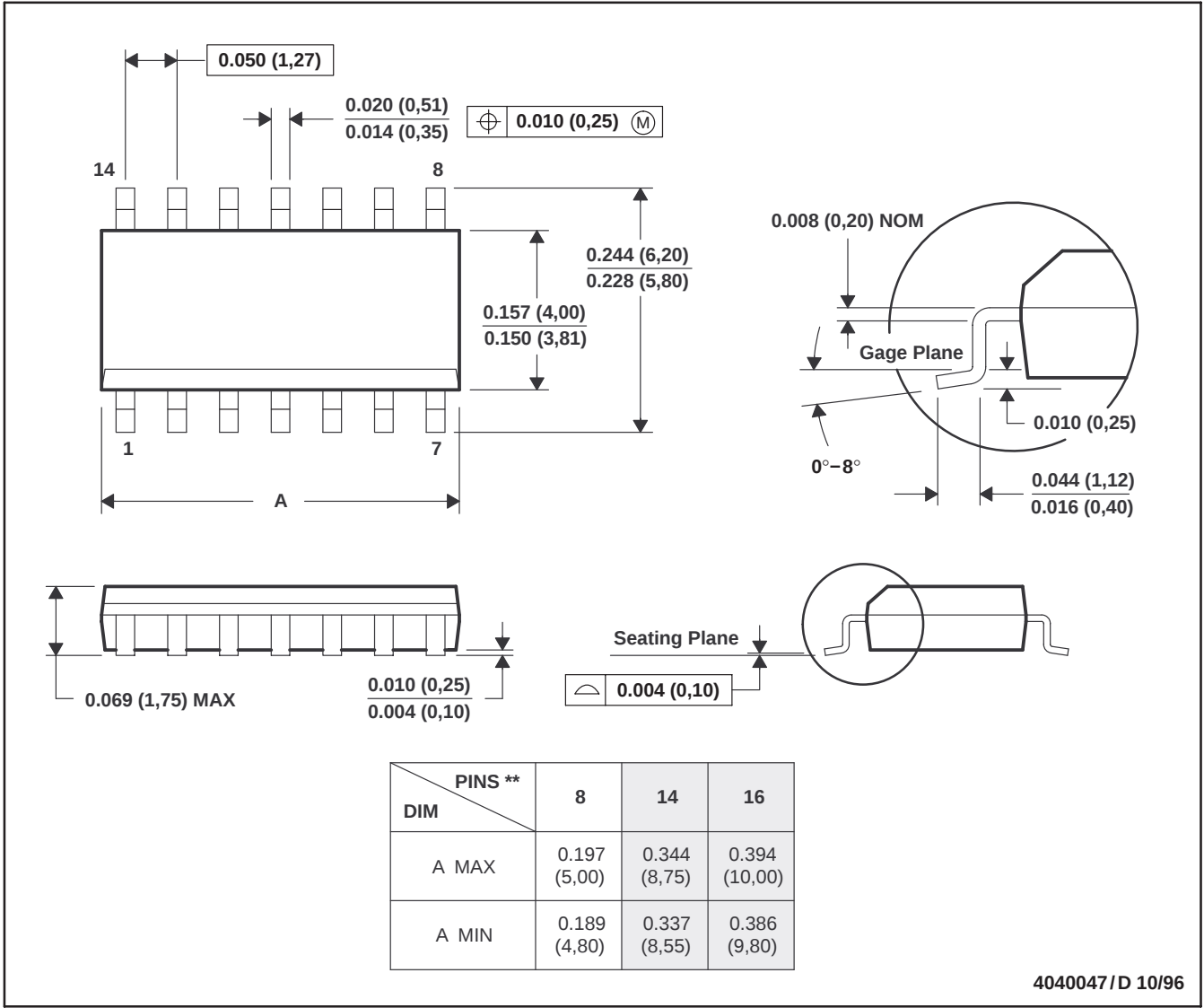
SGLS127 – JULY 2002

MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TLC3702MDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03643-01XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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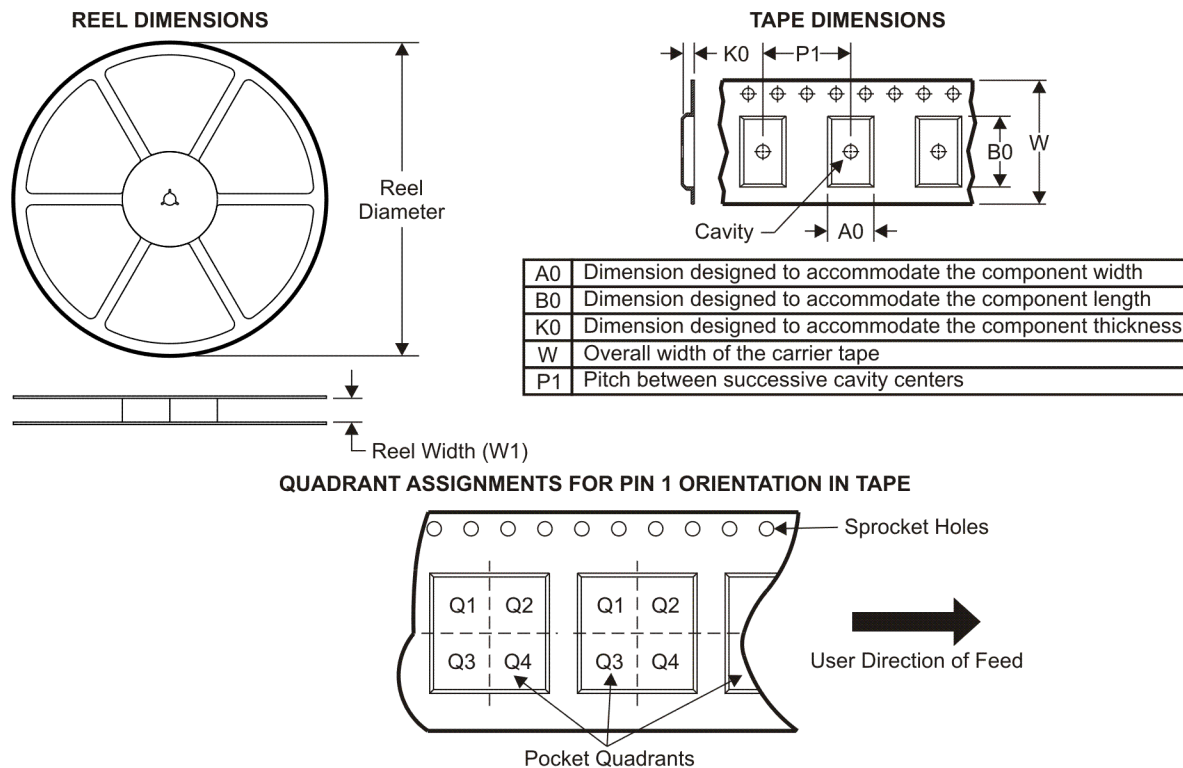
OTHER QUALIFIED VERSIONS OF TLC3702-EP :

- Catalog: [TLC3702](#)
- Automotive: [TLC3702-Q1](#)
- Military: [TLC3702M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

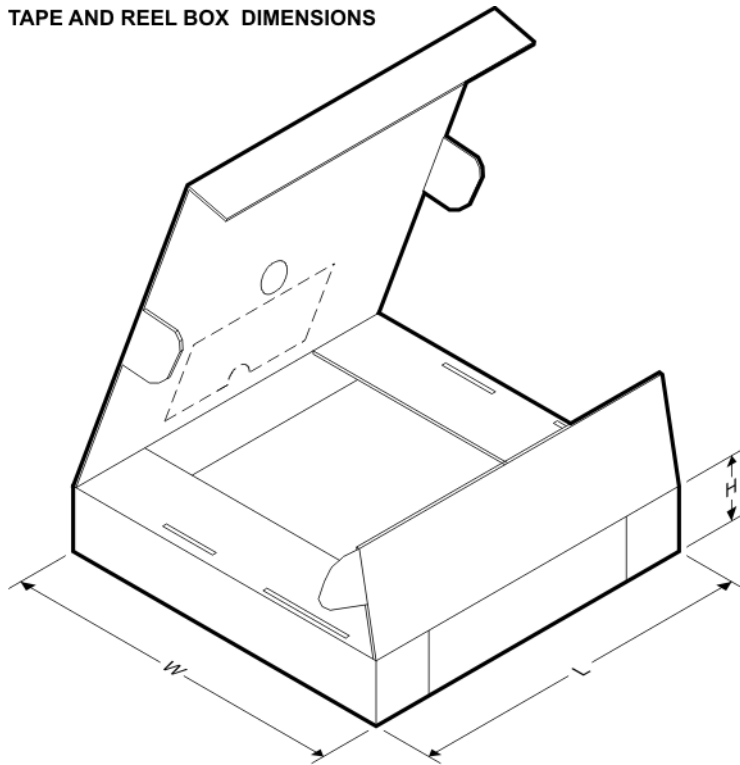
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC3702MDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

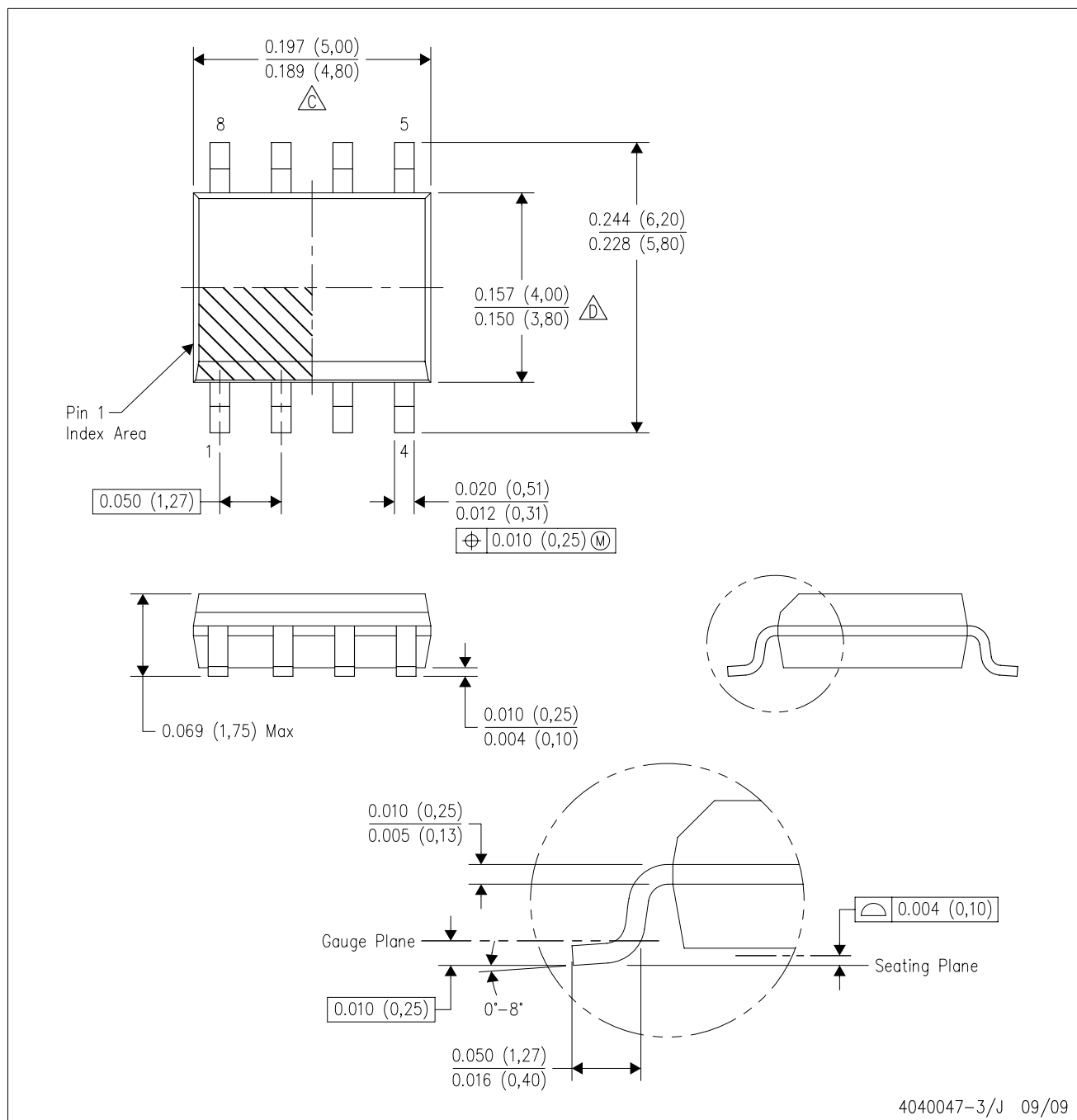


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC3702MDREP	SOIC	D	8	2500	346.0	346.0	29.0

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.

PACKAGING INFORMATION

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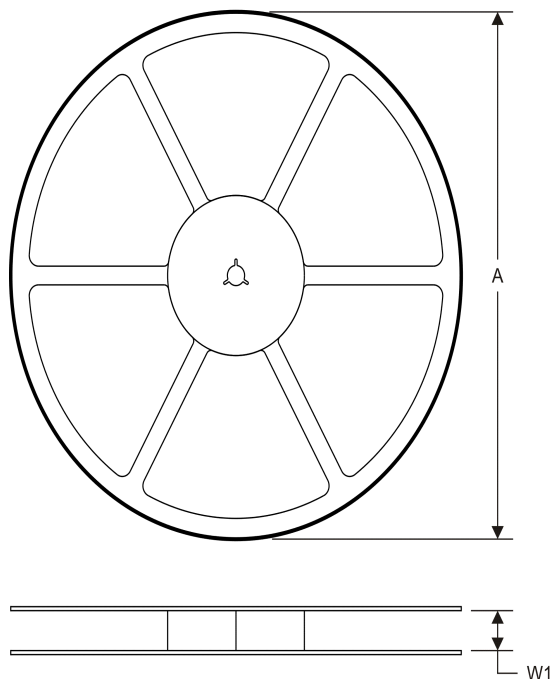
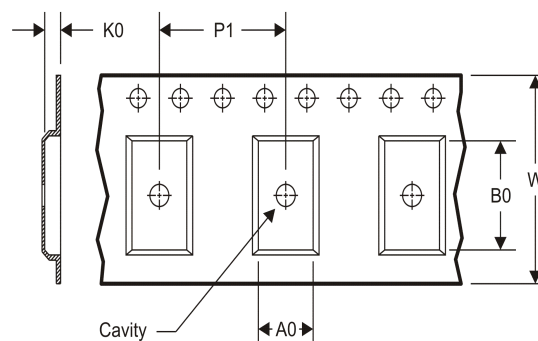
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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


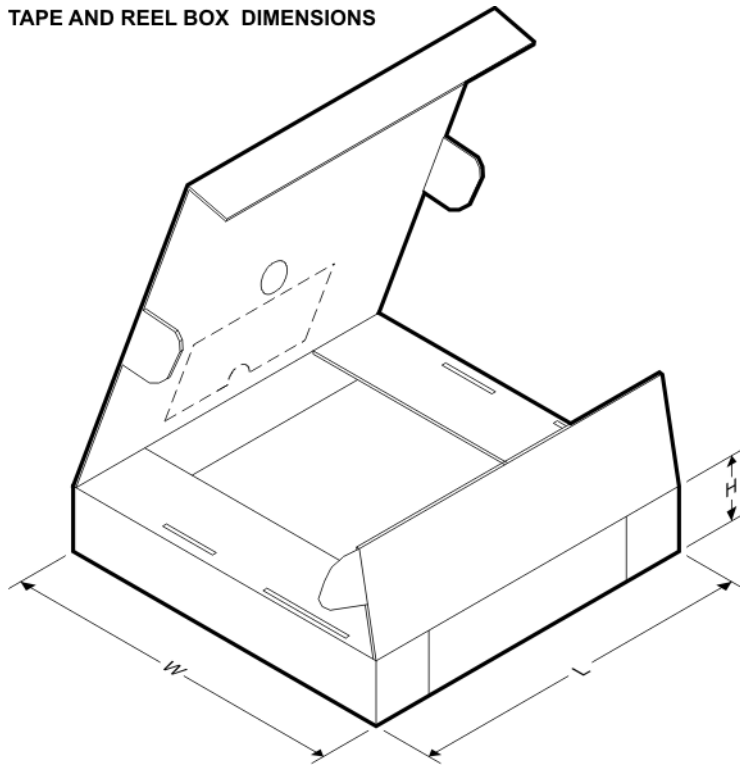
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
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TAPE AND REEL BOX DIMENSIONS

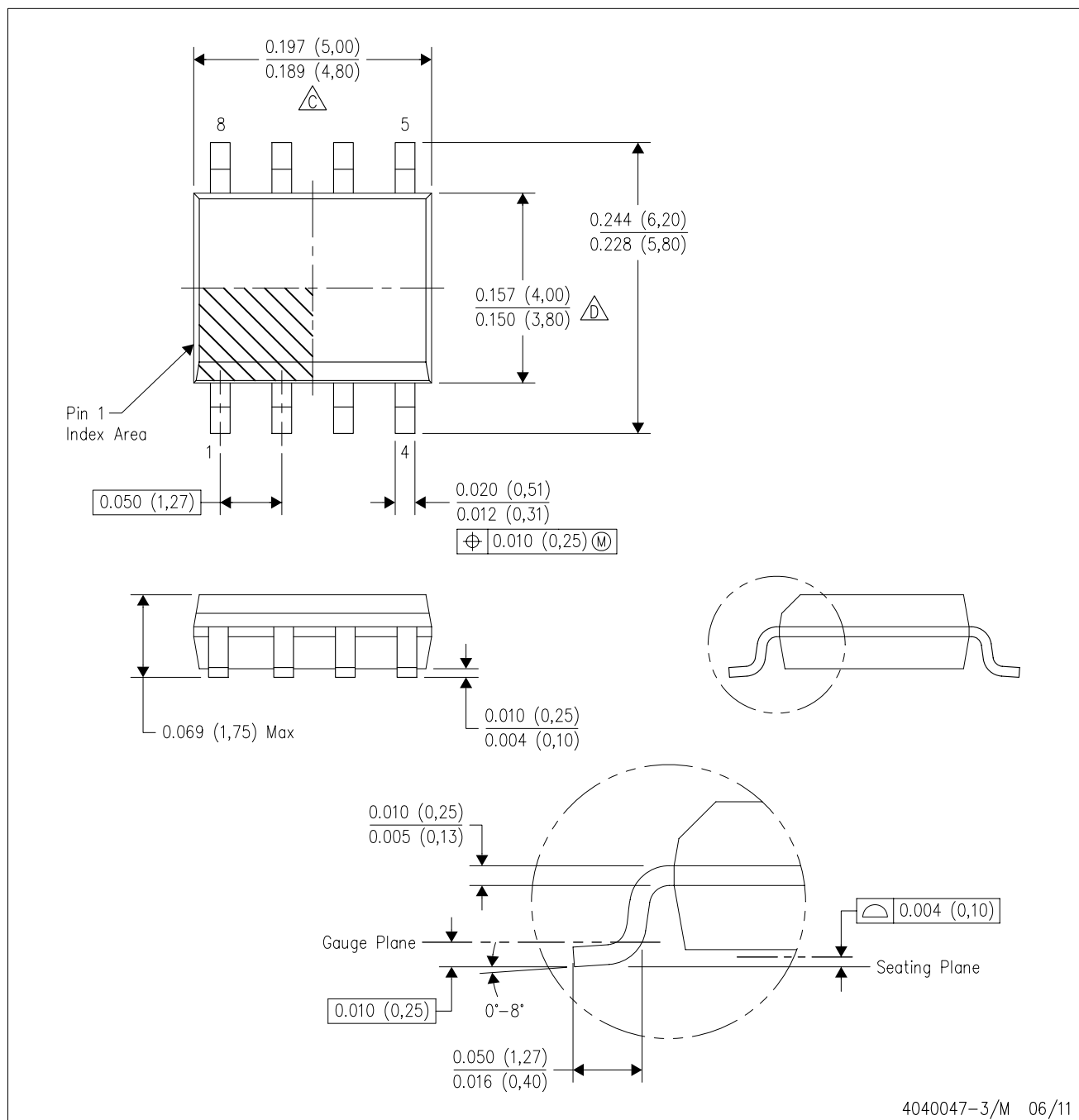


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC3702MDREP	SOIC	D	8	2500	367.0	367.0	35.0

D (R-PDSO-G8)

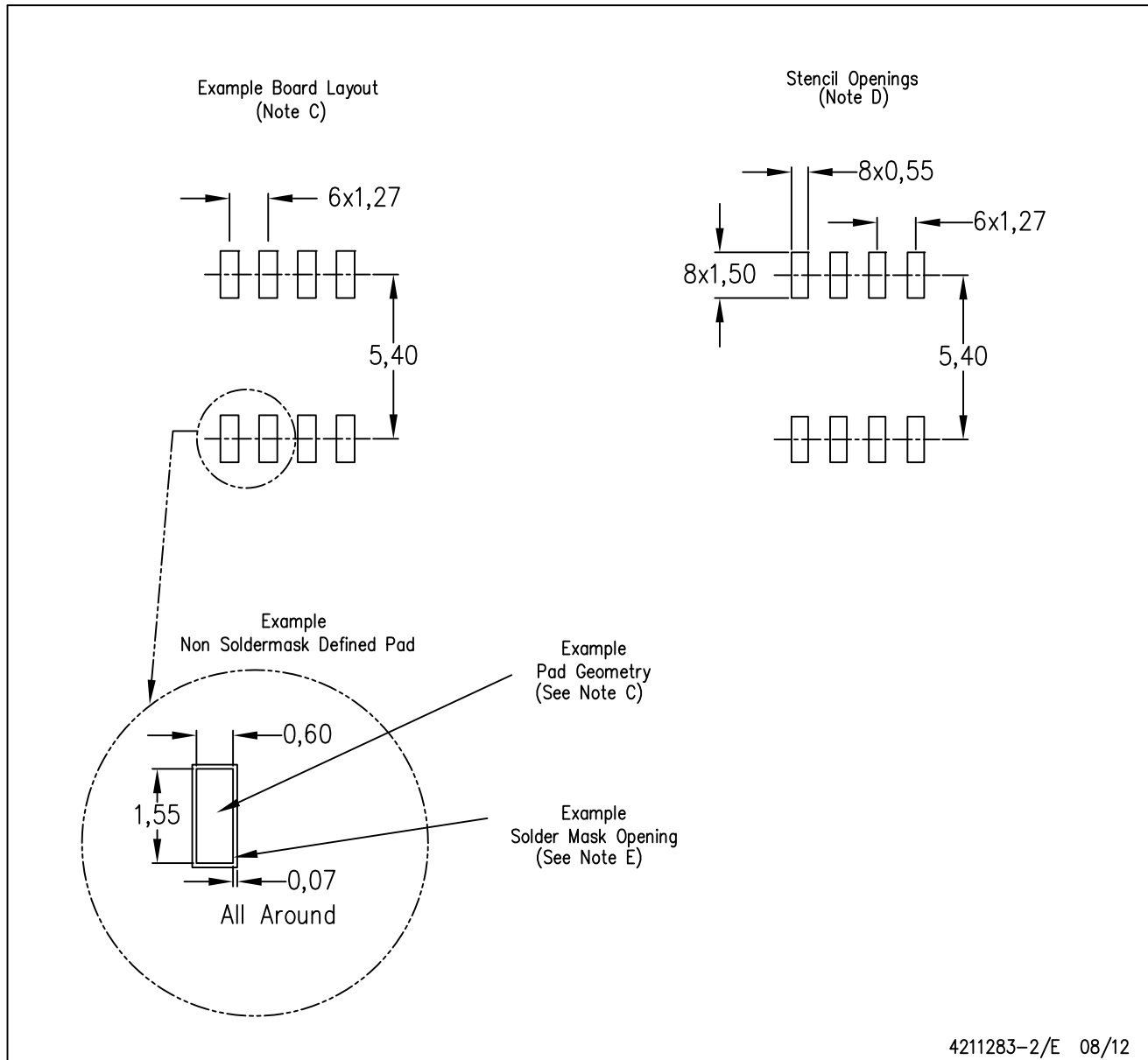
PLASTIC SMALL OUTLINE



- NOTES:
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 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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